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(54) Title: SAWING DEVICE AND METHOD FOR FORMING SAW-CUTS INTO A SEMICONDUCTOR PRODUCT

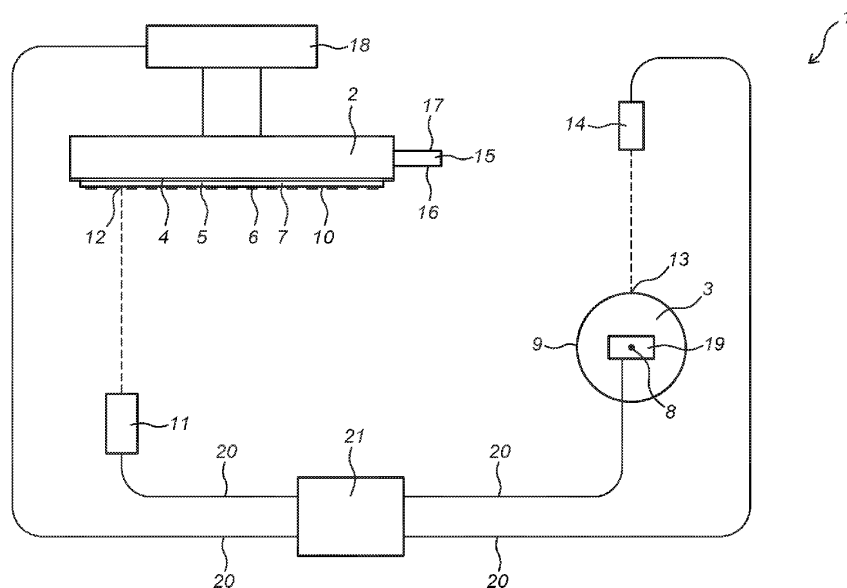


Fig. 1

(57) Abstract: The invention relates to a sawing device (1) for forming saw-cuts into a semiconductor product (5), comprising: a carrier (2) for holding the semiconductor product (5), a saw blade (3), a first position sensor (11) for determining the position of the semiconductor product (5) held by the carrier (2), a second position sensor (14) for determining the position of the saw blade (3), and a control unit (21) configured for controlling the relative movement of the saw blade (3) and the carrier (2), wherein the sawing device (1) further comprises a reference (15) for linking the position of the first position sensor (11) to the position of the second position sensor (14), wherein the control unit (21) is configured to process, with aid of the reference (15), the positions determined by the reference sensors (11, 14) into a position of the point on the free surface of the semiconductor product (5) relative to the point on the cutting edge (9) of the saw blade (3), and, based on this positional information, control the relative movement of the saw blade (3) and the carrier (2).

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